



## Koh Young Extends Invitation to the 2024 IEEE Electronic Components and Technology Conference in Denver, Colorado Opening May 28, 2024

Atlanta, GA – Koh Young, the industry leader in True3D™ measurement-based inspection solutions, invites you to join us at the 2024 IEEE Electronic Components and Technology Conference from May 28-31, 2024, in Denver, Colorado at the Gaylord Rockies Resort & Convention Center. The Electronic Components and Technology Conference (ECTC) is the premier international event that brings together the best in packaging, components and microelectronic systems science, technology and education in an environment of cooperation and technical exchange. Koh Young is proud to be the exclusive gala sponsor of the 74<sup>th</sup> ECTC.

The technical program includes papers covering leading edge developments and technical innovations across the packaging spectrum, including topics like assembly and manufacturing technology, advanced packaging, as well as emerging technologies in both poster and presentation formats. The panel, plenary, special sessions, and EPS seminar provide conference participants with an opportunity to gain insights and perspectives from industry leaders.

The ECTC Exhibition complements the strength of the ECTC technical program with an opportunity for engineers and decision makers to collaborate with Koh Young and other packaging companies. *“With our market-leading, AI-powered complement of inspection machines designed to reduce waste with zero-defect production via automated process control and autonomous optimization, we have the expertise and solutions to help manufacturers improve their processes,”* remarked Brent Fischthal, Head of Global Marketing at Koh Young. *“We will be in booth 724 during the exhibit hours and available to discuss your advanced packaging and wafer level inspection and application challenges.”*



Register to attend [here](#) or with the following link [ectc.net/registration](https://ectc.net/registration). If you cannot attend, you can still learn more about our best-in-class inspection solutions at [kohyoungamerica.com](https://kohyoungamerica.com).

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### About Koh Young Technology, Inc.

Established in 2002, Koh Young revolutionized the inspection market by launching the industry’s first 3D Solder Paste Inspection (SPI) system using a patented dual-projection Moiré technology. Since then, it has become the global leader in 3D measurement-based SPI and Automated Optical Inspection (AOI) equipment for the electronics industry. Based on its True3D™ measurement-based inspection technology, Koh Young has developed innovative inspection solutions for challenges with machined parts, press-fit and through-hole pins, conformal coatings, dispensed materials, and semiconductor packages. Through its constant innovation, Koh Young has secured over 3,600 global customers, and commands the dominant global market share position in the SPI and AOI markets with over 23,000 machine installations. A customer-centric R&D focus uses our core competencies to develop innovative solutions for new and existing markets by listening to users and researching trends and applications. From the headquarters in Korea, activities spread across the world through its global sales and support infrastructure spanning Europe, Asia, and the Americas. These regional offices ensure Koh Young stays close to the market, and more importantly, its growing user base. Learn why so many electronics manufacturers trust Koh Young for reliable inspection for a smart factory at our website at [www.kohyoungamerica.com](https://www.kohyoungamerica.com) or [www.kohyoung.com](https://www.kohyoung.com).

### For More Information

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